2.5V/3.3V 1:5 LVPECL **Fanout Buffer**

Description

The NB3L853141 is a low skew 1:5 LVPECL Clock fanout buffer designed explicitly for low output skew applications.

The NB3L853141 features a multiplexed input which can be driven by either a differential or single-ended input to allow for the distribution of a lower speed clock along with the high speed system clock.

The SEL pin will select the differential clock inputs, CLK0 & <u>CLKO</u>, when LOW (or left open and pulled LOW by the internal pull-down resistor). When SEL is HIGH, the single-ended CLK1 input is selected.

The common enable (\overline{EN}) is synchronous so that the outputs will only be enabled/disabled when they are already in the LOW state. This avoids any chance of generating a runt clock pulse when the device is enabled/disabled as can happen with an asynchronous control. The internal flip flop is clocked on the falling edge of the input clock, therefore, all associated specification limits are referenced to the negative edge of the clock input.

Features

- 700 MHz Maximum Clock Output Frequency
- CLK0 and CLK0 can Accept Differential LVPECL, LVDS, HCSL, LVHSTL, SSTL, LVCMOS
- CLK1 can Accept LVCMOS and LVTTL
- Five Differential LVPECL Clock Outputs
- 1.5 ns Maximum Propagation Delay
- Operating Range: $V_{CC} = 2.375 \text{ V}$ to 3.8 V
- LVCMOS Compatible Control Inputs
- Selectable Differential or LVCMOS Clock Inputs
- Synchronous Clock Enable
- 30 ps Max. Skew Between Outputs
- -40°C to +85°C Ambient Operating Temperature Range
- TSSOP-20 Package
- These are Pb-Free Devices

Applications

- Computing and Telecom
- Routers, Servers and Switches
- Backplanes

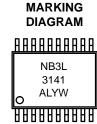


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CASE 948E



Α = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week = Pb-Free Package

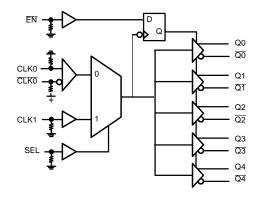
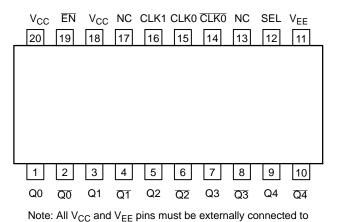


Figure 1. Simplified Logic Diagram of NB3L853141

ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet



Power Supply to guarantee proper operation.

Figure 1. Pinout (Top View) and Logic Diagram

Table 1. FUNCTION TABLE

CLK0	CLK1	SEL	EN	Q
L	Х	L	L	L
Н	X	L	L	Н
X	L	Н	L	L
X	Н	Н	L	Н
Х	Х	Х	Н	L*

*On next negative transition of CLK0 or CLK1 X = Don't Care

Table 2. PIN DESCRIPTION

Pin Number	Name	I/O	Open Default	Description
1	Q0	LVPECL Output		Non-Inverted Differential Clock Output
2	Q0	LVPECL Output		Inverted Differential Clock Output
3	Q1	LVPECL Output		Non-Inverted Differential Clock Output
4	Q1	LVPECL Output		Inverted Differential Clock Output
5	Q2	LVPECL Output		Non-Inverted Differential Clock Output
6	Q2	LVPECL Output		Inverted Differential Clock Output
7	Q3	LVPECL Output		Non-Inverted Differential Clock Output
8	Q3	LVPECL Output		Inverted Differential Clock Output
9	Q4	LVPECL Output		Non-Inverted Differential Clock Output
10	Q4	LVPECL Output		Inverted Differential Clock Output
11	VEE	Power		Negative Supply Voltage
12	SEL	LVCMOS / LVTTL Input	Low	Clock Select Input. When HIGH, selects CLK1 input. When LOW, selects CLK0, CLK0 inputs. Internal Pull–down Resistor.
13	NC			No Connect
14	CLK0	Multi-Level Input	High	Inverted Differential Clock Input. Internal Pull-up Resistor.
15	CLK0	Multi-Level Input	Low	Non-Inverted Differential Clock Input. Internal Pull-down Resistor.
16	CLK1	LVCMOS/LVTTL Input	Low	Single-ended Clock Input. Internal Pull-down Resistor.
17	NC			No Connect
18	VCC	Power		Positive Supply Voltage
19	ĒN	LVCMOS/LVTTL Input	Low	Synchronous Clock Enable Input. When Low, outputs are enabled. When High, outputs are disabled Low. Internal Pull–down Resistor.
20	VCC	Power		Positive Supply Voltage

All VCC and VEE pins must be externally connected to a power supply to guarantee proper operation. Bypass each supply pin with 0.01 μ F to GND.

Table 3. ATTRIBUTES (Note 1)

Characteris	Value			
ESD Protection Human Body Model Machine Model		> 2 kV > 200 V		
R _{PU} – Pull–up Resistor		50 kΩ		
R _{PD} – Pull–down Resistor		50 kΩ		
Moisture Sensitivity (Note 1)	TSSOP-20	Level 1		
Flammability Rating	UL*94 code V*0 @ 0.125 in			
Transistor Count	300			
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test				

^{1.} For additional information, see Application Note AND8003/D.

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	LVPECL Mode Power Supply	V _{EE} = 0 V		4.6	V
VI	LVPECL Mode Input Voltage	V _{EE} = 0 V	V _I ≤ V _{CC}	-0.5 to V _{CC} + 0.5	V
I _{out}	Output Current	Continuous Surge		50 100	mA mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-20 TSSOP-20	140 50	°C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-20	23 to 41	°C/W
T _{sol}	Wave Solder	<2 to 3 sec @ 260°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 5. DC CHARACTERISTICS $V_{CC} = 2.375 \text{ V}$ to 3.8 V; $V_{EE} = 0 \text{ V}$ (Note 2); $T_A = -40 ^{\circ}\text{C}$ to +85 $^{\circ}\text{C}$

Symbol	Characterist	ic	Min	Тур	Max	Unit
POWER SI	UPPLY		•		•	
V _{CC}	Power Supply Voltage		2.375		3.8	V
I _{EE}	Power Supply Current (Outputs Open)			40	55	mA
LVPECL O	UTPUTS (Note 3)					
V _{OH}	Output HIGH Voltage		V _{CC} -1.4		V _{CC} -0.9	V
V _{OL}	Output LOW Voltage		V _{CC} -2.0		V _{CC} -1.7	V
V _{SWING}	Output Voltage Swing, Peak-to-Peak		0.6		1.0	V
DIFFEREN	TIAL INPUTS DRIVEN SINGLE-ENDED (Note 4) (Figures 3 and 4)				
V _{IH}	Single-ended Input HIGH Voltage		0.5		V _{CC} +0.3	V
V _{IL}	Single-ended Input LOW Voltage		-0.3		V _{CC} -1.0	V
V_{th}	Input Threshold Reference Voltage Rang	e (Note 5)	0.35		V _{CC} -0.85	V
V _{ISE}	Single-ended Input Voltage (V _{IH} - V _{IL})		0.3		V _{CC}	V
DIFFEREN	TIAL INPUTS DRIVEN DIFFERENTIALLY	(see Figures 5 and 6) (Note 6)				
V_{IHD}	Differential Input HIGH Voltage		0.5		V _{CC} -0.85	mV
V_{ILD}	Differential Input LOW Voltage		0		V _{IHD} -150	mV
V_{ID}	Differential Input Voltage (V _{IHD} – V _{ILD})		0.15		1.3	V
V_{CMR}	Common Mode Input Voltage; (Note 7)		0.5		V _{CC} -0.85	
I _{IH}	Input HIGH Current	$V_{CC} = V_{IN} = 3.8 \text{ V} \frac{\text{CLK0}}{\text{CLK0}}$			150 5	μΑ
I _{IL}	Input LOW Current	$V_{CC} = 3.8V$, $V_{IN} = 0$ V $\frac{CLK0}{CLK0}$	–5 –150			μΑ
SINGLE-E	NDED INPUTS (SEL, EN, CLK1)					
V _{IH}	Input HIGH Voltage	SEL, <u>EN</u> CLK1	2.0 2.0		V _{CC} +0.3 V _{CC} +0.3	V
V _{IL}	Input LOW Voltage	SEL, EN CLK1	-0.3 -0.3		0.8 V _{CC} x0.35	V
I _{IH}	Input HIGH Current VCC = V _{IN} = 3.8 V	CLK1, SEL, EN			150	μΑ
I _{IL}	CLK1, SEL, EN	CLK1, SEL, EN	- 5			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

- circuit board with maintained transverse airliow greater than 500 irpm.
 2. Input and Output parameters vary 1:1 with V_{CC} .
 3. LVPECL outputs loaded with 50 Ω to V_{CC} 2 V for proper operation.
 4. V_{th} , V_{IH} , V_{IL} , and V_{ISE} parameters must be complied with simultaneously.
 5. V_{th} is applied to the complementary input when operating in single—ended mode.
 6. V_{IHD} , V_{ILD} , V_{ID} and V_{CMR} parameters must be complied with simultaneously.
 7. The common mode voltage is defined as V_{IH} .

Table 6. AC CHARACTERISTICS, $V_{CC} = 2.375 \text{ V}$ to 3.8 V, $T_A = -40^{\circ}\text{C}$ to +85°C (Note 8)

Symbol	Characteristic	Characteristic				Max	Unit
f _{MAX}	Maximum Input Clock Frequency: V _{OUTpp} ≥ 400 mV	CLK0/CL	K0, V _{INPPmin} ≥ 250 mV CLK1	700 300			MHz
Φ_{N}	Phase Noise, f _C = 155.52 MHz	10 Hz 100 Hz 1 kHz 10 kHz 100 kHz 1 MHz 10 MHz 20 MHz	Offset from Carrier		-100.5 -128.2 -138.6 -147.1 -149.7 -154.2 -154.2 -154.2		dBc/ Hz
t _{PLH} , t _{PHL}	Propagation Delay to Differential Outputs, @ 50 MHz	Note 9 Note 10	CLK0/CLK0 to Q/Q CLK1 to Q	0.8 0.8	1.0 1.0	1.5 1.5	ns
t∫⊕N	Additive Phase Jitter, RMS; f _C = 155.52 MHz, Integration Range: 12 kHz – 20 MHz				0.05		ps
tsk(o)	Output-to-output skew; (Note 11)					30	ps
tsk (pp)	Part-to-Part Skew; (Note 12)					150	ps
V_{INpp}	Input Voltage Swing/Sensitivity (Differential Configuration	ion) (Note 1	4)	150		1300	mV
t _r /t _f	Output rise and fall times, 20% to 80%,		Q, Q	200		700	ps
ODC	Output Clock Duty Cycle CLK0/CLK0 Input Duty Cycle = 50%	0, f ≤ 700 M	Hz, V _{INPPmin} ≥ 250 mV CLK1, f ≤ 250MHz	45 45		55 55	%

All parameters measured at f_{MAX} unless noted otherwise.

The cycle-to-cycle jitter on the input will equal the jitter on the

output. The part does not add jitter

^{8.} Measured using a $V_{INPPmin}$ source, Reference Duty Cycle = 50% duty cycle clock source. All output loading with external 50 Ω to $V_{CC}-2$ V.

Measured from the differential input crossing point to the differential output crossing point.
 Measured from V_{CC}/2 input crossing point to the differential output crossing point.

^{11.} Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the output differential cross points.

^{12.} Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

13. Output voltage swing is a single–ended measurement operating in differential mode.

^{14.} Input voltage swing is a single-ended measurement operating in differential mode.

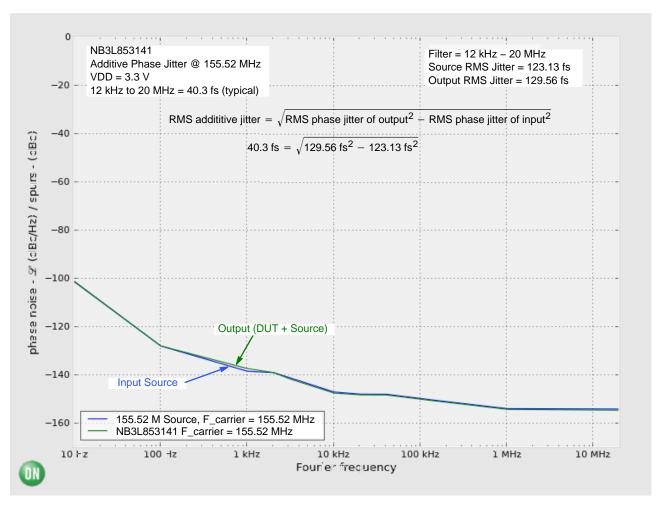


Figure 2. Typical Phase Noise Plot at f_{carrier} = 155.52 MHz at an Operating Voltage of 3.3 V, Room Temperature

The above phase noise data was captured using Agilent E5052A/B. The data displays the input phase noise and output phase noise used to calculate the additive phase jitter at a specified integration range. The RMS Phase Jitter contributed by the device (integrated between 12 kHz and 20 MHz) is 40.3 fs.

The additive phase jitter performance of the fanout buffer is highly dependent on the phase noise of the input source.

To obtain the most accurate additive phase noise measurement, it is vital that the source phase noise be

notably lower than that of the DUT. If the phase noise of the source is greater than the device under test output, the source noise will dominate the additive phase jitter calculation and lead to an artificially low result for the additive phase noise measurement within the integration range. The Figure above is a good example of the NB3L853141 source generator phase noise having a significantly higher floor such that the DUT output results in an additive phase jitter of 40.3 fs.

RMS addititive jitter =
$$\sqrt{\text{RMS phase jitter of output}^2 - \text{RMS phase jitter of input}^2}$$

 $40.3 \, \text{fs} = \sqrt{129.56 \, \text{fs}^2 - 123.13 \, \text{fs}^2}$

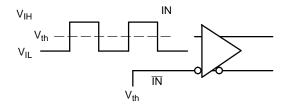


Figure 3. Differential Input Driven Single-Ended

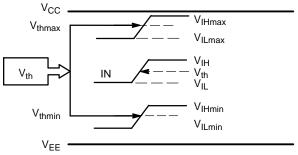


Figure 4. V_{th} Diagram

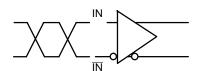
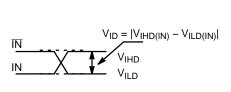


Figure 5. Differential Inputs Driven Differentially



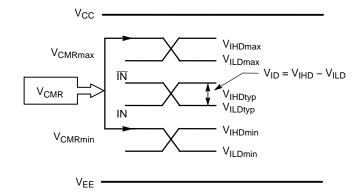


Figure 6. Differential Inputs Driven Differentially

Figure 7. VCMR Diagram

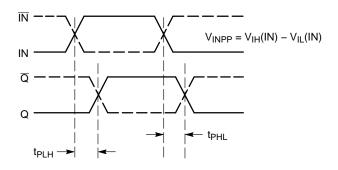


Figure 8. AC Reference Measurement

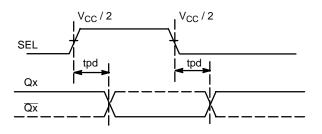


Figure 9. SEL to Qx Timing Diagram

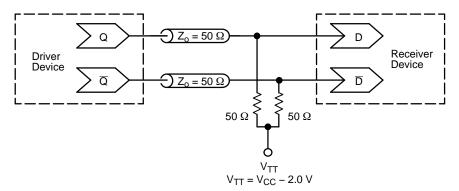


Figure 10. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

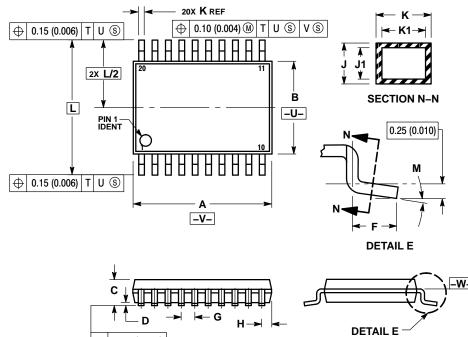
ORDERING INFORMATION

Device	Package	Shipping [†]
NB3L853141DTG	TSSOP-20 (Pb-Free)	75 Units / Rail
NB3L853141DTR2G	TSSOP-20 (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

TSSOP-20 CASE 948E-02 **ISSUE C**



0.100 (0.004)

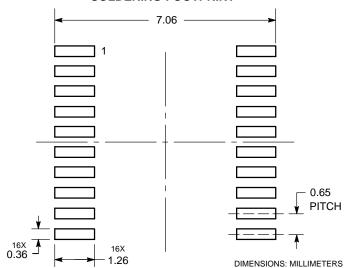
-T- SEATING PLANE

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- FLASH, PROTRUSIONS OR GATE BURRS.
 MOLD FLASH OR GATE BURRS SHALL NOT
 EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE
 INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION
 SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 DIMENSION K DOES NOT INCLUDE
 DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION. SHALL BE 0.08
 (0.003) TOTAL IN EXCESS OF THE K
- (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE
 DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
Н	0.27	0.37	0.011	0.015
7	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252	BSC
M	0°	8°	0°	8°

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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